

Amendments to the Claims:

This listing of claims will replace the listing of claims, as filed and as amended in the First Preliminary Amendment, in the application:

Listing of Claims:

Claim 1 (original): An organic light emitting diode device having a passivation layer comprising boron oxide.

Claim 2 (currently amended): A device according to claim 1, comprising a substrate, a layer of organic ~~preferably polymeric~~, light emitting material, and a transparent cathode comprising a layer of material with a work function less than 4 eV.

Claim 3 (original): A device according to claim 2, wherein said material with a work function of less than 4 eV comprises calcium.

Claims 4-8 (canceled).

Claim 9 (original): A method of manufacturing an organic light emitting diode device, comprising depositing a passivation layer comprising boron oxide on the device.

Claim 10 (original): A method according to claim 9, wherein said passivation layer is deposited by thermal evaporation.

Claims 11-18 (canceled).

Claim 19 (original): A passivation layer for an electronic device, the passivation layer comprising boron oxide.

Claim 20 (new): A device according to claim 2, wherein said light emitting material is a polymeric light emitting material.

Claim 21 (new): A device according to claim 2, wherein said passivation layer directly overlies said layer of material with a work function less than 4 eV.

Claim 22 (new): A device according to claim 1, further comprising an encapsulating layer overlying said passivation layer.

Claim 23 (new): A device according to claim 22, wherein said encapsulating layer comprises a dielectric oxide selected from a group consisting of Al_2O_3 , SiO_2 , TiO_2 , ZrO_2 , MgO , HfO_2 , Ta_2O_5 , aluminum titanium oxide, and tantalum hafnium oxide.

Claim 24 (new): A device according to claim 1, further comprising sealing layers of adhesive and glass.

Claim 25 (new): A device according to claim 24, wherein said adhesive comprises epoxy resin.

Claim 26 (new): A method according to claim 9, wherein the device comprises a substrate, a layer of organic light emitting material, and a transparent cathode comprising a layer of material with a work function less than 4 eV.

Claim 27 (new): A method according to claim 26, wherein said passivation layer is deposited directly onto said layer of material with a work function less than 4 eV.

Claim 28 (new): A method according to claim 9, further comprising a step of depositing an encapsulating layer onto said passivation layer.

Claim 29 (new): A method according to claim 28, wherein said encapsulating layer comprises a dielectric oxide selected from a group consisting of Al_2O_3 , SiO_2 , TiO_2 , ZrO_2 , MgO , HfO_2 , Ta_2O_5 , aluminum titanium oxide, and tantalum hafnium oxide.

Claim 30 (new): A method according to claim 28, wherein said encapsulating layer is deposited by electron beam evaporation.

Claim 31 (new): A method according to claim 28, wherein said encapsulating layer is deposited by sputtering.

Claim 32 (new): A method according to claim 9, further comprising the step of sealing the device with an adhesive and glass.

Claim 33 (new): A method according to claim 9, comprising the step of adapting the thickness of said passivation layer to energy of electrons, ions, or fields from which protection is required.